**Preferred Device** 

# Small Signal MOSFET 200 mAmps, 60 Volts

N-Channel TO-92

#### **MAXIMUM RATINGS**

| Rating   | Symbol                              | Value          | Unit        |
|--|-------------------------------------|----------------|-------------|
| Drain Source Voltage   | V <sub>DSS</sub>                    | 60             | Vdc         |
| Drain–Gate Voltage (R <sub>GS</sub> = 1.0 M $\Omega$ )                       | V <sub>DGR</sub>                    | 60             | Vdc         |
| Gate–Source Voltage  – Continuous  – Non–repetitive (t <sub>p</sub> ≤ 50 μs) | V <sub>GS</sub><br>V <sub>GSM</sub> | ±20<br>±40     | Vdc<br>Vpk  |
| Drain Current - Continuous - Pulsed  | I <sub>D</sub>                      | 200<br>500     | mAdc        |
| Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C            | PD                                  | 350<br>2.8     | mW<br>mW/°C |
| Operating and Storage Temperature Range                                      | T <sub>J</sub> , T <sub>stg</sub>   | –55 to<br>+150 | °C          |

#### THERMAL CHARACTERISTICS

| Characteristic  | Symbol         | Max | Unit |
|---|----------------|-----|------|
| Thermal Resistance, Junction to Ambient   | $R_{	heta JA}$ | 357 | °C/W |
| Maximum Lead Temperature for Soldering Purposes, 1/16" from case for 10 seconds | TL             | 300 | °C   |

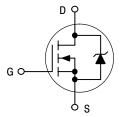


# ON Semiconductor

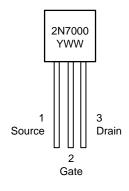
http://onsemi.com

200 mAMPS 60 VOLTS RDS(on) = 5  $\Omega$ 

N-Channel







Y = Year WW = Work Week

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

# 2N7000

# **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

| Characteristic   |  | Symbol              | Min           | Max         | Unit         |
|--|--|---------------------|---------------|-------------|--------------|
| OFF CHARACTERISTICS  |  |                     |               |             |              |
| Drain–Source Breakdown Voltage (V <sub>GS</sub> = 0, I <sub>D</sub> = 10 μAdc)   |  | V(BR)DSS            | 60            | _           | Vdc          |
| Zero Gate Voltage Drain Current (VDS = 48 Vdc, VGS = 0) (VDS = 48 Vdc, VGS = 0, TJ = 125°C)  |  | IDSS                | <u>-</u><br>- | 1.0<br>1.0  | μAdc<br>mAdc |
| Gate-Body Leakage Current, Forward (VGSF = 15 Vdc, VDS = 0)  |  | <sup>I</sup> GSSF   | _             | -10         | nAdc         |
| ON CHARACTERISTICS (N  | ote 1.)  |                     |               | 1           | •            |
| Gate Threshold Voltage (VDS = VGS, ID = 1.0 mAdc)  |  | V <sub>GS(th)</sub> | 0.8           | 3.0         | Vdc          |
| Static Drain–Source On–Resistance ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 0.5 \text{ Adc}$ ) ( $V_{GS} = 4.5 \text{ Vdc}$ , $I_D = 75 \text{ mAdc}$ ) |  | rDS(on)             | <u>-</u><br>- | 5.0<br>6.0  | Ohm          |
| Drain–Source On–Voltage ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 0.5 \text{ Adc}$ ) ( $V_{GS} = 4.5 \text{ Vdc}$ , $I_D = 75 \text{ mAdc}$ )           |  | VDS(on)             | -<br>-        | 2.5<br>0.45 | Vdc          |
| On–State Drain Current<br>(V <sub>GS</sub> = 4.5 Vdc, V <sub>DS</sub> = 10 Vdc)  |  | I <sub>d(on)</sub>  | 75            | _           | mAdc         |
| Forward Transconductance<br>(V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 200 mAdc)  |  | 9fs                 | 100           | _           | μmhos        |
| DYNAMIC CHARACTERIST   | rics   | -                   |               |             | *            |
| Input Capacitance  | (V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0,              | C <sub>iss</sub>    | -             | 60          | pF           |
| Output Capacitance   |  | C <sub>oss</sub>    | -             | 25          | 1            |
| Reverse Transfer<br>Capacitance  | f = 1.0 MHz)   | C <sub>rss</sub>    | -             | 5.0         |              |
| SWITCHING CHARACTERI   | STICS (Note 1.)  |                     |               | •           | •            |
| Turn-On Delay Time   | (V <sub>DD</sub> = 15 V, I <sub>D</sub> = 500 mA,          | ton                 | _             | 10          | ns           |
| Turn-Off Delay Time  | $R_G = 25 \Omega$ , $R_L = 30 \Omega$ , $V_{gen} = 10 V$ ) | <sup>t</sup> off    | -             | 10          |              |

<sup>1.</sup> Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

# 2N7000

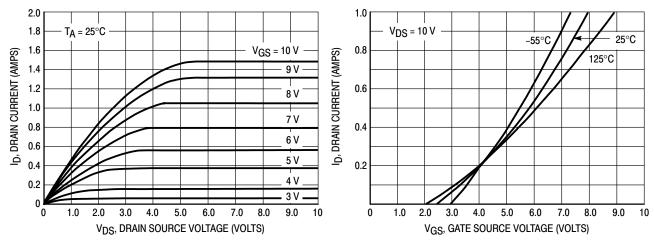


Figure 1. Ohmic Region

Figure 2. Transfer Characteristics

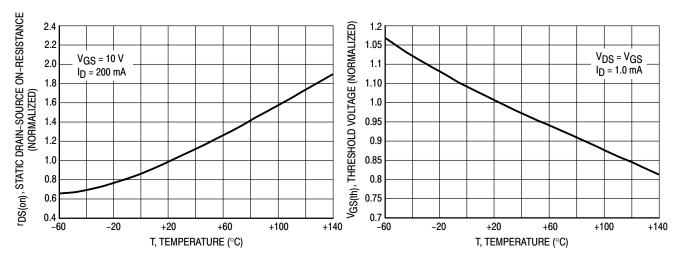


Figure 3. Temperature versus Static Drain–Source On–Resistance

Figure 4. Temperature versus Gate Threshold Voltage

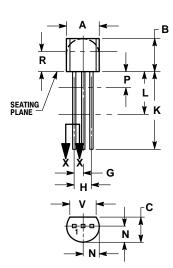
### **ORDERING INFORMATION**

| Device     | Package | Shipping         |
|------------|---------|------------------|
| 2N7000     | TO-92   | 1000 Unit/Box    |
| 2N7000RLRA | TO-92   | 2000 Tape & Reel |
| 2N7000RLRM | TO-92   | 2000 Ammo Pack   |
| 2N7000RLRP | TO-92   | 2000 Ammo Pack   |
| 2N7000ZL1  | TO-92   | 2000 Ammo Pack   |

#### 2N7000

#### PACKAGE DIMENSIONS

TO-92 CASE 29-11 ISSUE AL





- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  - CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R
- IS UNCONTROLLED.
  LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

|     | INCHES |       | MILLIN | IETERS |
|-----|--------|-------|--------|--------|
| DIM | MIN    | MAX   | MIN    | MAX    |
| Α   | 0.175  | 0.205 | 4.45   | 5.20   |
| В   | 0.170  | 0.210 | 4.32   | 5.33   |
| С   | 0.125  | 0.165 | 3.18   | 4.19   |
| D   | 0.016  | 0.021 | 0.407  | 0.533  |
| G   | 0.045  | 0.055 | 1.15   | 1.39   |
| Н   | 0.095  | 0.105 | 2.42   | 2.66   |
| J   | 0.015  | 0.020 | 0.39   | 0.50   |
| K   | 0.500  |       | 12.70  |        |
| L   | 0.250  |       | 6.35   |        |
| N   | 0.080  | 0.105 | 2.04   | 2.66   |
| P   |        | 0.100 |        | 2.54   |
| R   | 0.115  |       | 2.93   |        |
| V   | 0.135  |       | 3 43   |        |

STYLE 22: PIN 1. SOURCE 2.

GATE 3 DRAIN

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